Room A

09:00

[16A-1] SiP/PoP Advanced Assembly Ⅰ

1. PoP Technology for Mobile Phone Manufacturing – Past, Present and Future (Session Invite)
   Y.Wada (Nokia Japan)/Japan
2. 3D Technology Roadmap and the Global Competition (Session Invite)
   H.Nakajima (NEC Electronics)/Japan
3. Flip Chip SiP and Advances (Session Invite)
   H.Shimamoto (Renessas)/Japan
4. (Session Invite)
   A New Novel Dual Face Package
   M.Ishihara (Kyushu Institure of Technology)/Japan

10:40

10:50

[16A-2] SiP/PoP Advanced Assembly Ⅱ

1. Gold Stud Bumps for Hight Performance Flip Chip Packages
   W.Chen[1], K.Shen[1], A.Wang[1], Y.Lai[1], B.Appelt[2], A.Tseng[2] ([1]Advanced Semiconductor Enginrrring, [2]ASE(US))/Taiwan, USA
2. Novel Compact Connector for PoP and BoB Applications
   K.-S.Choi[1], H.-C.Bae[1], D.-S.Jun[1], J.-T.Moon[1], K.-B.Cha[2], D.-Y.Kim[2], Y.-I.Jun[1] ([1]Electonics and Telecommnucations Resarch Institute, [2]Unisemicon)/Korea
3. Wettability and Reliability on Double Side Assembly with MPS-C2 Flip Chip Technology
   H.Noma, Y.Oyama, H.Nishiwaki, M.Takami, T.Takatani, K.Toriyama, Y.Orii (IBM Japan)/Japan
4. Effect of Packaging Process Parameters on the Damage of Semiconductor Device with Low-k Materials
   M.Masumoto[1], O.Horiuchi[2], T.Yamada[2], J.Morishita[3], W.Choi[4], H.Tomokage[4] ([1]Texas Instruments, [2]Fukuoka Industry, Science & Technology Foundation, [3]Walts, [4]Fukuoka University)/Japan

12:30

12:30–13:30 **Lunch time / Poster Session**

13:30

[16A-3] Fine MEMS Ⅰ

1. Nano-mechanical Structure Fabrication Technology for Highly Integrated, Complex MEMS (Tentative) (Session Invite)
   I. Shimoyama (The University of Tokyo)/Japan (Tentative)
2. High Density Integration Technology with Laser Assisted Inkjet Writing (Session Invite)
   J.Akedo (National Institute of Advanced Industrial Science and Technology)/Japan
3. Highly Integrated MEMS-Pseudo-SOC Technology (Session Invite)
   H.Yamada (Toshiba)/Japan

(14:45)

(14:55)

[16A-4] Fine MEMS Ⅱ

1. High Density Packaging Technology Using Low Temperature Chip Stacking for Fine-MEMS (Tentative) (Session Invite)
   M.Koyanagi, T.Fukushima, T.Tanaka (Tohoku University)/Japan (Tentative)
2. Mass-production Technology for Vertical Integrated MEMS (Session Invite)
   S.Lee (OMRON)/Japan
3. Wafer-Level Bonding Technology for Different Materials (Session Invite)
   E.Shimizu, T.Suyama, R.Ohta (Olympus)/Japan

(16:10)

(16:20)

[16A-5] Assembly Technology for MEMS

1. A Novel Microfabricated Fibrillar Structure Inspired from Biological Attachment Systems
   H.Parsaiyan, F.Barazandeh, S.M.Rezaei, M.S.Hajhashem (Amirkabir University of Technology)/Iran
2. Parylene Embedded Metal Interconnects for Stretchable Silicon Electronics
   T.Zoumpoulidis[1], M.Bartek[1], R.Dekker[1,2] ([1]Delft University of Technology, [2]Philips Research)/The Netherlands
3. Laser Assisted Ink Jet Printing for Fine Ag Wiring
   A.Endo, J.Akedo (National Institute of Advanced Industrial Science and Technology)/Japan
4. Development of Wafer Level CSP for Micro Electro Mechanical Systems
   H.Tenmei[1], K.Matsumoto[2], M.Nakajima[2], M.Sugita[2], S.Nagashima[2] ([1]Hitachi, [2]Hitachi Media Electronics)/Japan
5. Low Temperature Wafer Bonding using Metal Diffusion Technique
   H.Kurotaki[1], H.Shinohara[2], H.Kobayashi[1], J.Mizuno[2], S.Shoji[2] ([1]EV Group Japan, [2]Waseda University)/Japan

(18:25)

15:10 / 15:20 / 18:50

Room B1

[16B1-1] Material Ⅰ

1. Low-temperature Curable and Electrically Conductive Paste for Touch Panels and LCD Panels
   J.Bai, R.Chu, S.Gupta (Henkel Japan)/Japan
2. The Effect of Conductive Particle Parameters on Electronical Conductvity in Anisotropic Conductive Film Joints
   J.-H.Kuang, C.-M.Hsu (National Sun Yat-Sen Universtity)/Taiwan
3. Study of the Filler Effect on the Effective Thermal Conductivity of Thermal Conductive Adhesive
   Y.Zhang[1], C.Yue[1], J.Liu[1,2], Z.Cheng[2], J.-Y.Fan[1] ([1]Shanghai University, [2]Chalmers University of Technology)/China, Sweden
4. Thermal Conductivity of Electrically Conductive Adhesives Containing Fillers with Multi-modal Paricle Size Distibutions
   M.Inoue[1], J.Liu[2,3] ([1]Osaka University, [2]Chalmers University of Technology, [3]Shanghai University)/Japan, Sweden, China

[16B1-2] MEMS / TSV Key Technologies

1. Micropump with Cross-junction Channels for Application in Gas Rate Sensor
   V.T.Dau, K.Tanaka, S.Sugiyama (Ritsumeikan University)/Japan
2. An Investigation into Deep RIE-based Through-Si-Via(TSV) Microfabrication for 3-D System-in-package(SiP) Integration
   M.Miao[1,2], Y.Jin[1], H.Liao[1], L.Zhao[1], Y.Zhu[1], X.Sun[1] ([1]Peking University, [2]Beijing Information Science and Technology University)/China
3. Cu Fill Properties in the High Aspect Ratio Through Si Via Hole by Electroless Plating
   F.Inoue[1], K.Yamamoto[2], S.Tanaka[2], Z.Wang[3], S.Shingubara[1] ([1]Kansai Uninersity, [2]National Institute of Communication Technology, [3]Shaanxi Normal University)/Japan, China
4. Electrohydrodynamic Micropumps for Electronic Chip Cooling Applications (Session Invite)
   P.R.Selvaganapathy, C.Y.Ching(McMaster University)/Canada

Lunch time / Poster Session

[16B1-3] Automotive Electronics, Future Requirements

1. Launch-up of Adopting BGA into Engine ECU in Japan (Session Invite)
   H.Ueda (SemiConsult)/Japan
2. Development of IGBT Power Module with Anodized Metal Substrate (AMS) for Hybrid Electric Vehicle (HEV) Application (Session Invite)
   S.Gao, J.Kim, D.Yoo, S.Choi, S.Yi (Samsung Electro-Mechanics)/Korea
3. Design Concepts of New Components for Next Generation Automotive Power Electronics (Session Invite)
   T.Tominaga (CalsonicKansei)/Japan
4. Ink Jet Marking on Bare Die for Chip Traceability (Session Invite)
   H.Kawaguchi (Toray Engineering)/Japan

[16B1-4] Automotive Electronics, Challenges

1. Thermal Management of LED Headlamp System (Session Invite)
   S.Gao, S.Shin, Y.Lee, J.Kim, S.Choi, S.Yi (Samsung Electro-Mechanics)/Korea
2. Pb-free High Temperature Solder Joints for Power Semiconductor Device (Session Invite)
   Y.Yamada[1], Y.Takaku[2], Y.Yagi[1], I.Nakagawa[3], T.Atsumi[3], M.Shirai[3], I.Ohnuma[4], K.Ishida[4] ([1]Toyota Central Research & Development Laboratories, [2]Tohoku University CREST-JST, [3]Toyota Motor, [4]Tohoku University)/Japan
3. High Relaibility Solder for Car Electronics (Session Invite)
   M.Ueshima (Senju Metal Industry)/Japan
4. Drop Impact Reliability and Thermal Cycle Resistivity of Low-Ag Content Sn-Ag-Cu Solders (Session Invite)
   T.Sasaki (Nippon Steel)/Japan

(17:00)

(17:10)

[16B1-5] Electrical Solutions Ⅲ

1. Novel Highly-Integrated Common-Mode Resonant Filters Based on Multilayer Board Technologies
   T.Kushta (NEC)/Japan
2. Bond Pass Filter Embedded System with Probe (SwP) for High Frequency Application
   K.Matsumoto, R.Saito, W.Choi, H.Tomokage (Fukuoka University)/Japan
3. Reduction of EMI from Differential Signaling System Using Asymmetry Guard Trace
   T.Matsushima[1], Y.Toyota[1], K.Iokibe[1], R.Koga[1], T.Watanabe[2], O.Wada[3] ([1]Okayama University, [2]Industrial Technology Center of Okayama Prefecture, [3]Kyoto University)/Japan
4. Prediction of EM Radiation from a Printed Circuit Board Driven by Differential-Signaling
   Y.Kayano, H.Inoue (Akita University)/Japan

Room B2

[16B2-1] MFG/Process Ⅰ

1. Design of Experiment (DOE) Study for the Optimization of Lapping Process of GaAs Wafer for Wireless Device Application
   N.H.Ghazali, N.A.Omar, N.A.Ngah, A.Dolah, M.R.Yahya (Telekom Research & Development)/Malaysia
2. A Forming Method of Cavity Structure with LTCC Substrate Using Photo Resist Film
   Y.Akagi (Nihon University)/Japan
3. Inductive Modeling of Laser Trimming of Film Resistors
   J.Autonov (The Ulyanovsk State Technical University)/Russia
4. Influence of Deformation of Single Crystalline Copper on its Surface Activated Bonding at Room Temperature
   R.Takagishi, M.Akaike, T.Suga (The University of Tokyo)/Japan

[16B2-2] MFG/Process Ⅱ

1. Studies on Low-temperature Direct Bonding Methods of PMMA and COP Using Surface Pretreatment
   H.Shinohara, J.Mizuno, S.Shoji (Waseda University)/Japan
2. High Reliability Encapsulant Liquid Resin for SIP - The Simultaneous Process of over Mold and Underfill by VPES(Vacuum Printing Encapsulation Systems)
   K.Nagai, Y.Ishikawa, A.Okuno (SANYU REC)/Japan
3. A Novel Metal-to-metal Bonding Process Utilizing Low-temperature Sinterability of Ag_2O^- derived Ag Nanoparticles
   N.Takeda[1], H.Tatsumi[1], Y.Akada[1], T.Ogura *[1], E.Ide[2], T.Morita[2], A.Hirose[1] ([1]Osaka University, [2]Hitachi)/Japan
4. Assembly Technique of 0402size Chip on Flexible Printed Circuits
   T.Kitada (Fujikura)/Japan.

Lunch time / Poster Session

[16B2-3] MFG/Process Ⅲ

1. Die Product Assembly on Flex Substrate
   T.Onishi (Grand Joint Technology)/Hong Kong
2. Investigation of Flip Chip Bonding with NCF
   N.Asahi, K.Fujimaru, T.Nishiyama, K.Kasumi, K.Matsumura, T.Nonaka (Toray Industries)/Japan
3. Flip Chip Bonding with Elasticity Bonding System (EBS) Method
   R.Kojima (Sony Chemical & Information Device)/Japan
4. Effect of the Excimer Irradiation Process on the Interconnection of Flip Chip Bonding
   K.Sakuma[1,2], N.Nagai[1], J.Mizuno[1], S.Shoji[1] ([1]Waseda University, [2]IBM)/Japan

[16B2-4] Substrate Ⅰ

1. Microstructural and Dielectric Characterization of Alumina-Based LTCC Materials
   A.Ibrahim[1], R.Alias[1], M.H.A.R.M.Ahmad[2], C.S.Mahmood[2], M.R.Yahya[1], A.F.A.Mat[1] ([1]Telekom Research & Development, [2]MTEC)/Malaysia
2. Thermal Conductivity Characterization of Al_2O_3-SiO_2-PbO-MgO Tape System for High Frequency Substrate
   R.Alias, A.Ibrahim, S.M.Shapee, Z.Ambak, Z.M.Yusoff, M.R.Saad (Telekom Research & Development)/Malaysia
3. Multi-layer Thick Film Circuits with Silver Via Holes Built by All Screen-printing Process
   J.Rufiange (DKN Research)/USA

(16:35)

(16:45)

[16B2-5] Substrate Ⅱ

1. Reliability of Rigid to Flex Interconnection after Reflow
   K.Kawate (Sumitomo 3M)/Japan
2. Low Transmisson Loss and Excellent Heat Resistance Material for Muti-layer PCBs
   Y.Kitai (Panasonic Electric Works)/Japan
3. Development of High Density All Layer IVH PWB with Cavity Structure
   K.Honjo (Panasonic Electronic Devices)/Japan

(18:00)

Room K

[16K-1] RF / RFID Ⅰ

1. Experimental Study of the Isolation Performance of 0.18-um CMOS RF Bond Pad
   M.A.Ismail, N.F.I.Muhammad, A.I.A.Rahim, M.R.Yahya, A.F.A.Mat (Telekom Research & Development)/Malaysia
2. The Thin Type Electromagnetic Wave Absorption Wall Having Optical Ray Passage Property
   Y.Okano (Musashi Institute of Technology)/Japan
3. Development of System that Recognizes Conglomerate RF-ID Tag in UHF Band
   M.Ochiai (Musashi Institute of Technology)/Japan
4. Development of Small Tunable Antenna for Multi-frequency Band
   H.Fukasawa (Musashi Institute of Technology)/Japan

[16K-2] RF / RFID Ⅱ

1. Development of the Meosurement System of Sheet Resistance at Microwave Frequency Range Using DFFC
   T.Tosaka, A.Nishitaka, K.Fukunaga, Y.Yamanaka (NICT)/Japan
2. Evaluation of High Frequency Characteristics of FPC during Bending
   T.Tanaka (Nitto Denko)/Japan
3. Utilizing Scalable Model to Fast Synthesize High Performance RF Integrated Passive Circuits Applited to SiP Module
   C.-C.Wang[1], H.-A.Yang[1], J.Chen[1], T.-C.Lin[1], C.-T.Chiu[1], S.-M.Wu[2], C.-W.Kuo[3], C.-P.Hung[1] ([1]Advanced Semiconductor Engineering, [2]National University of Kaohsiung, [3]National Sun Yat-Sen University)/Taiwan
4. High Performance RF Intergrted Possive Circuits Design on Glass Wafer
   C.-C.Wang[1], H.-A.Yang[1], J.Chen[1], M.-H.Li[2], C.-T.Chiu[1], S.-M.Wu[2], C.-W.Kuo[3], C.-P.Hung[1] ([1]Advanced Semiconductor Engineering, [2]National University of Kaohsiung, [3]National Sun Yat-Sen University)/Taiwan
5. Band Pass Filter Design and Optimization on High-Resistivity Silicon for 5GHz RF Front End Receiver
   Y.Tsuchiya (IBIDEN)/Japan

(12:55)

Lunch time / Poster Session

(13:55)

[16K-3] Reliability

1. Failure Analyses and Lifetime Parameters for Lifetime Monitor of VIA Structures on Printed Circuit Boards
   M.Fujino, T.Suga (The University of Tokyo)/Japan
2. Study on Improving the Drop Impact Reliability of Plastic Core Solder Ball
   R.-D.Sun, N.Okinaga, K.Matsushita, M.Okuda (Sekisui Chemical)/Japan
3. Solder Joint Lifetime Evaluation of WLP and Cause
   T.Matsuzaki (CASIO COMPUTER)/Japan
4. Impact Reliability Studies of Sn-Ag-Cu-Ni BGA Solder Joints on Electroless Ni-P/Au Surface Finish
   F.Kawashiro (NEC Electronics)/Japan
5. Effects of Multiple Reflows on Interfacial Reactions and Shear Strength of SnAgCu Sojder Joints with Cu-Zn Wetting Layer
   Y.M.Kim, S.W.Ma, Y.-H.Kim (Hanyang University)/Korea

(16:00)

(16:10)

[16K-4] Material Ⅱ

1. Eco-fabrication of Noble Metal Nanoparticles by Metal Oxide and Home Electronics Appliances
   Y.Hayashi[1], M.Inoue[2], I.Narita[3], H.Takizawa[1], K.Suganuma[2] ([1]Tohoku Univeristy, [2]Osaka University, [3]Kyushu University)/Japan
2. Preparation and Optical Properties of 30 and 60nm Co_3O_4 Nanowires
   Y.-C.Chen (Feng-Chia University)/Taiwan
3. Molecular Modification of PCB Substrates: Demonstration of HAST Survivability of Fine-Line Patterned Structures
   S.Shi, T.Wei, Z.Liu, C.Rhodine, W.Kuhr (ZettaCore)/USA
4. Development of Thick Resist for Solder Bump
   K.Mori (JSR)/Japan
5. High-speed Power Supply System by Low Characteristic Impedance Transmission Lines Using Metamaterials
   K.Hashimoto[1], Y.Akiyama[1], T.Kawaguchi[2], K.Tahara[2], K.Otsuka[1] ([1]Meisei University, [2]Shin-Etsu Polymer)/Japan

(18:15)